500mA Fixed Output CMOS LDO

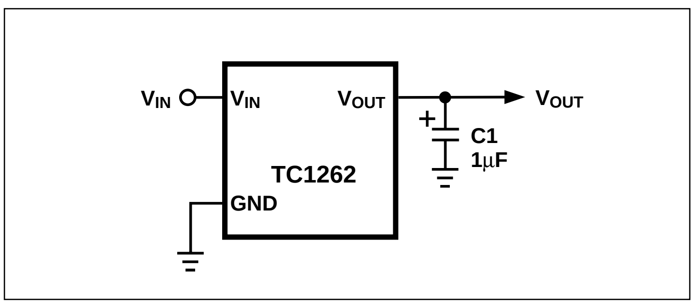
FEATURES

- Very Low Dropout Voltage
- Guaranteed 500mA Output
- High Output Voltage Accuracy
- Standard or Custom Output Voltages
- Over-Current and Over-Temperature Protection

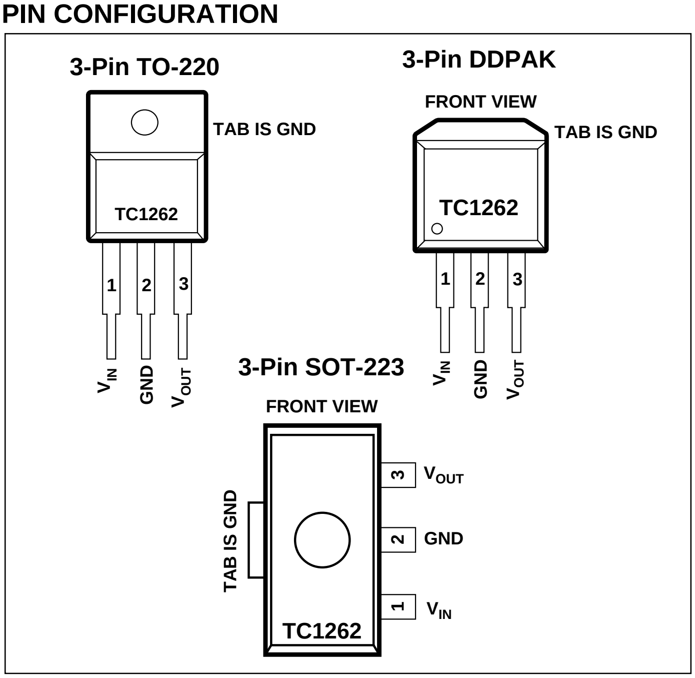
APPLICATIONS

- Battery-Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular / GSM / PHS Phones
- Linear Post-Regulator for SMPS
- Pagers

TYPICAL APPLICATION



PIN CONFIGURATION



GENERAL DESCRIPTION

The TC1262 is a fixed output, high accuracy (typically ±0.5%) CMOS low dropout regulator. Designed specifically for battery-operated systems, the TC1262's CMOS construction eliminates wasted ground current, significantly extending battery life. Total supply current is typically 80 µA at full load *(20 to 60 times lower than in bipolar regulators*).

TC1262 key features include ultra low noise, very low dropout voltage (typically 350mV at full load), and fast response to step changes in load. The TC1262 incorporates both over-temperature and over-current protection. The TC1262 is stable with an output capacitor of only 1µF and has a maximum output current of 500mA. It is available in 3-Pin SOT-223, 3-Pin TO-220, and 3-Pin DDPAK packages.

ORDERING INFORMATION

Part Number	Package	Junction Temp. Range
TC1262-xxVDB	3-Pin SOT-223	– 40°C to +125°C
TC1262-xxVAB	3-Pin TO-220	– 40°C to +125°C
TC1262-xxVEB	3-Pin DDPAK	– 40°C to +125°C

Available Output Voltages:
2.5, 2.8, 3.0, 3.3, 5.0
xx indicates output voltages

Other output voltages are available. Please contact Microchip Technology Inc. for details.

TC1262

ABSOLUTE MAXIMUM RATINGS*

Input Voltage 6.5V
Output Voltage .... (V_{SS} – 0.3) to (V_{IN} + 0.3)
Power Dissipation .... Internally Limited (Note 6)
Operating Temperature .... – 40°C < T_J < 125°C
Storage Temperature .... – 65°C to +150°C
Maximum Voltage on Any Pin .... V_{IN} + 0.3V to – 0.3V
Lead Temperature (Soldering, 10 Sec.) .... +260°C

*Absolute Maximum Ratings indicate device operation limits beyond damage may occur. Device operation beyond the limits listed in Electrical Characteristics is not recommended.

ELECTRICAL CHARACTERISTICS:

$V_{IN} = V_{OUT} + 1V$, $I_L = 100\mu A$, $C_L = 3.3\mu F$, $T_A = 25°C$, unless otherwise specified. **BOLDFACE** type specifications apply for junction temperatures of – 40°C to +125°C.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
V_{IN}	Input Operating Voltage		—	—	**6.0**	V
I_{OUTMAX}	Maximum Output Current		**500**	—	—	mA
V_{OUT}	Output Voltage	Note 1	— **V_R – 2.5%**	V_R ± 0.5% —	— **V_R + 2.5%**	V
$\Delta V_{OUT}/\Delta T$	V_{OUT} Temperature Coefficient	Note 2	—	40	—	ppm/°C
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	$(V_R + 1V) \leq V_{IN} \leq 6V$	—	.003	**0.35**	%
$\Delta V_{OUT}/V_{OUT}$	Load Regulation	I_L = 0.1mA to I_{OUTMAX} (Note 3)	—	0.002	**0.01**	%/mA
$V_{IN} – V_{OUT}$	Dropout Voltage (Note 4)	I_L = 100µA I_L = 100mA I_L = 300mA I_L = 500mA	— — — —	20 60 200 350	**30** **130** **390** **650**	mV
I_{DD}	Supply Current	I_L = 0	—	80	**130**	µA
PSRR	Power Supply Rejection Ratio	$F_{RE} \leq$ 1KHz	—	64	—	dB
I_{OUTSC}	Output Short Circuit Current	V_{OUT} = 0V	—	1200	—	mA
$\Delta V_{OUT}/\Delta P_D$	Thermal Regulation	Note 5	—	0.04	—	V/W
eN	Output Noise	$I_L = I_{OUTMAX}$	—	260	—	$nV/\sqrt{Hz}$

NOTES:
1. V_R is the regulator output voltage setting.
2. $T_C V_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$
3. Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
4. Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.
5. Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{LMAX} at V_{IN} = 6V for T = 10 msec.
6. The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature, and the thermal resistance from junction-to-air (i.e. T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see *Thermal Considerations* section of this data sheet for more details.

DETAILED DESCRIPTION

The TC1262 is a precision, fixed output LDO. Unlike bipolar regulators, the TC1262 supply current does not increase with load current. In addition, V_{OUT} remains stable and within regulation at very low load currents (an important consideration in RTC and CMOS RAM battery backup applications). Figure 1 shows a typical application circuit.

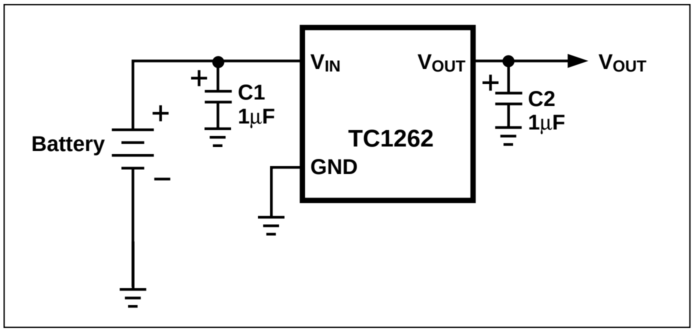


Figure 1: Typical Application Circuit

Output Capacitor

A 1µF (min) capacitor from V_{OUT} to ground is required. The output capacitor should have an effective series resistance of 5Ω or less, and a resonant frequency above 1 MHz. A 1µF capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately –30°C, solid tantalums are recommended for applications operating below –25°C.) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

Thermal Considerations

Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 160°C. The regulator remains off until the die temperature drops to approximately 150°C.

Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case *actual* power dissipation:

$$P_D \approx (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX}$$

Where:
P_D = worst case actual power dissipation
V_{INMAX} = maximum voltage on V_{IN}
V_{OUTMIN} = minimum regulator output voltage
$I_{LOADMAX}$ = maximum output (load) current

Equation 1.

The maximum *allowable* power dissipation (Equation 2) is a function of the maximum ambient temperature (T_{AMAX}), the maximum allowable die temperature (125°C) and the thermal resistance from junction-to-air (θ_{JA}).

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

Where all terms are previously defined.

Equation 2.

Table 1 shows various values of θ_{JA} for the TC1262 mounted on a 1/16 inch, 2-layer PCB with 1 oz. copper foil.

Table 1. Thermal Resistance Guidelines for TC1262 in SOT-223 Package

Copper Area (Topside)*	Copper Area (Backside)	Board Area	Thermal Resistance (θ_{JA})
2500 sq mm	2500 sq mm	2500 sq mm	45°C/W
1000 sq mm	2500 sq mm	2500 sq mm	45°C/W
225 sq mm	2500 sq mm	2500 sq mm	53°C/W
100 sq mm	2500 sq mm	2500 sq mm	59°C/W
1000 sq mm	1000 sq mm	1000 sq mm	52°C/W
1000 sq mm	0 sq mm	1000 sq mm	55°C/W

NOTES: *Tab of device attached to topside copper

Table 2. Thermal Resistance Guidelines for TC1262 in 3-Pin DDPAK/TO-220 Package

Copper Area (Topside)*	Copper Area (Backside)	Board Area	Thermal Resistance (θ_{JA})
2500 sq mm	2500 sq mm	2500 sq mm	25°C/W
1000 sq mm	2500 sq mm	2500 sq mm	27°C/W
125 sq mm	2500 sq mm	2500 sq mm	35°C/W

NOTES: *Tab of device attached to topside copper

Equation 1 can be used in conjunction with Equation 2 to ensure regulator thermal operation is within limits. For example:

TC1262

GIVEN: V_{INMAX} = 3.3V ± 10%
V_{OUTMIN} = 2.7V ± 0.5%
I_{LOAD} = 275mA
T_{AMAX} = 95°C
θ_{JA} = 59°C/W (SOT-223)

FIND: 1. Actual power dissipation
2. Maximum allowable dissipation

Actual power dissipation:

$$P_D \approx (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX}$$
$$= [(3.3 \times 1.1) - (2.7 \times .995)]275 \times 10^{-3}$$
$$= \underline{260mW}$$

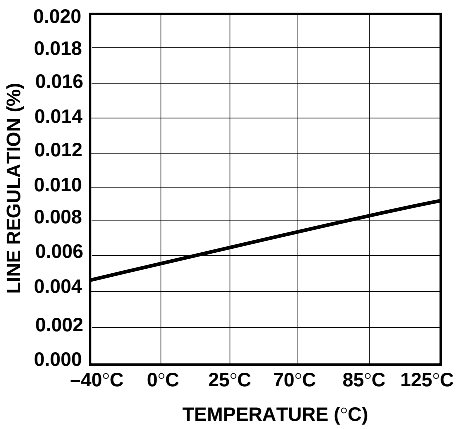
Maximum allowable power dissipation:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$
$$= \frac{(125 - 95)}{59}$$
$$= \underline{508mW}$$

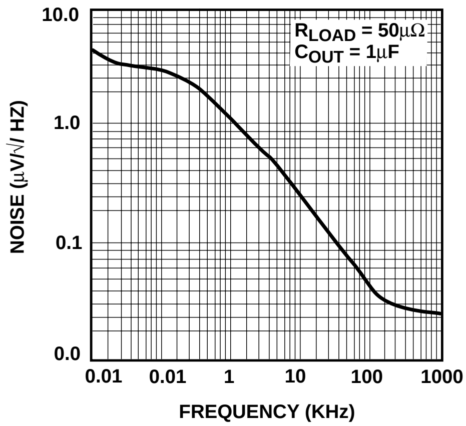
In this example, the TC1262 dissipates a maximum of only 260mW; far below the allowable limit of 508mW. In a similar manner, Equation 1 and Equation 2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable V_{IN} is found by substituting the maximum allowable power dissipation of 508mW into Equation 1, from which V_{INMAX} = 4.6V.

TYPICAL CHARACTERISTICS

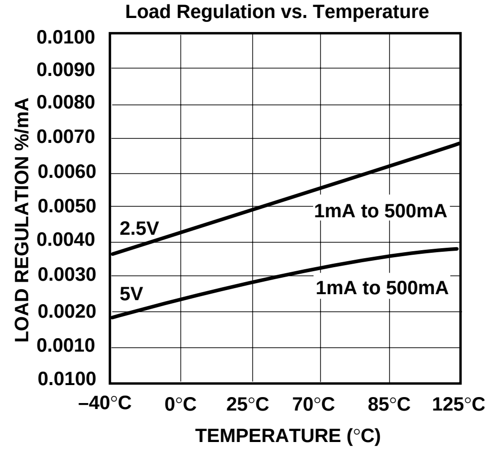
Line Regulation vs. Temperature



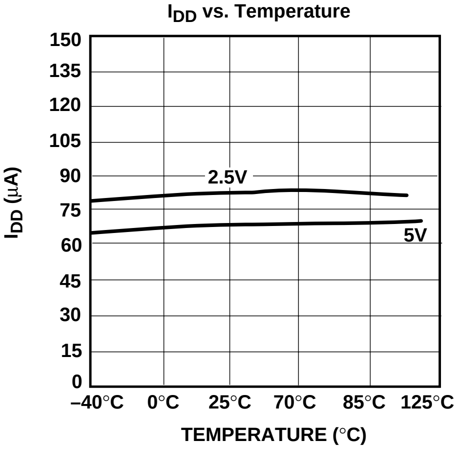
Output Noise vs. Frequency



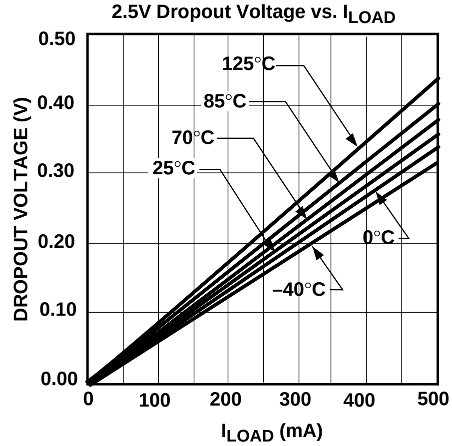
Load Regulation vs. Temperature



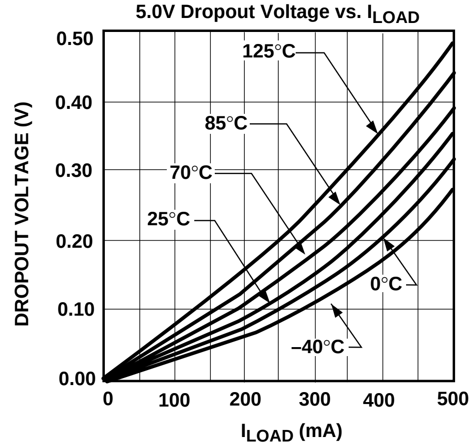
I_{DD} vs. Temperature



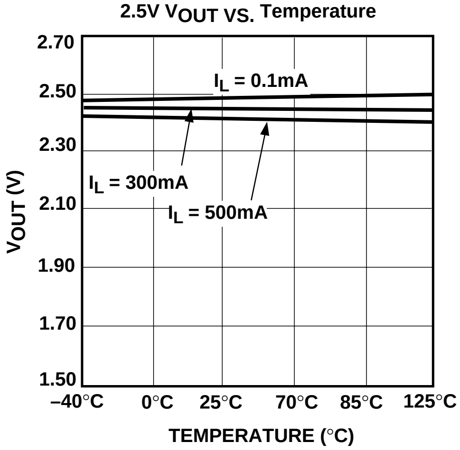
2.5V Dropout Voltage vs. I_{LOAD}



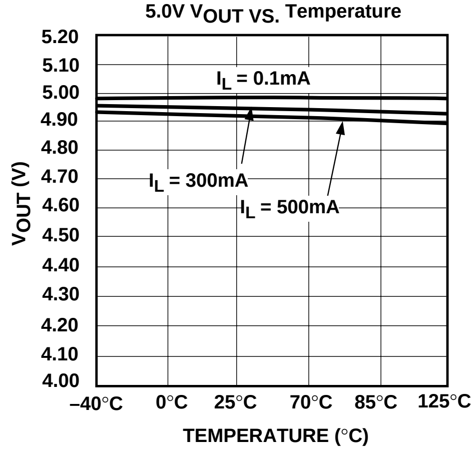
5.0V Dropout Voltage vs. I_{LOAD}



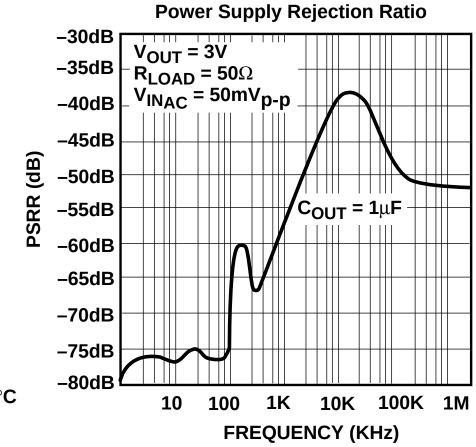
2.5V V_{OUT} VS. Temperature



5.0V V_{OUT} VS. Temperature



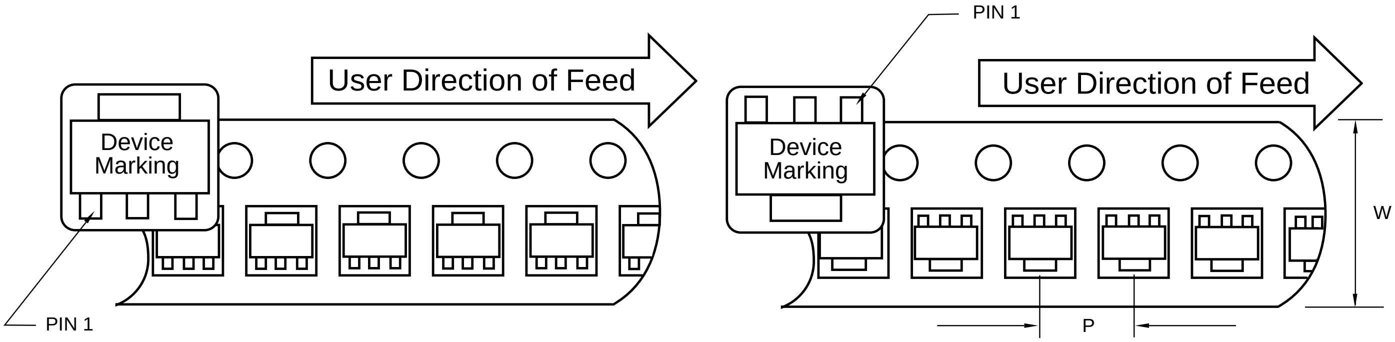
Power Supply Rejection Ratio



TC1262

TAPING FORMS

Component Taping Orientation for 3-Pin SOT-223 Devices



Standard Reel Component Orientation
for TR Suffix Device
(Mark Right Side Up)

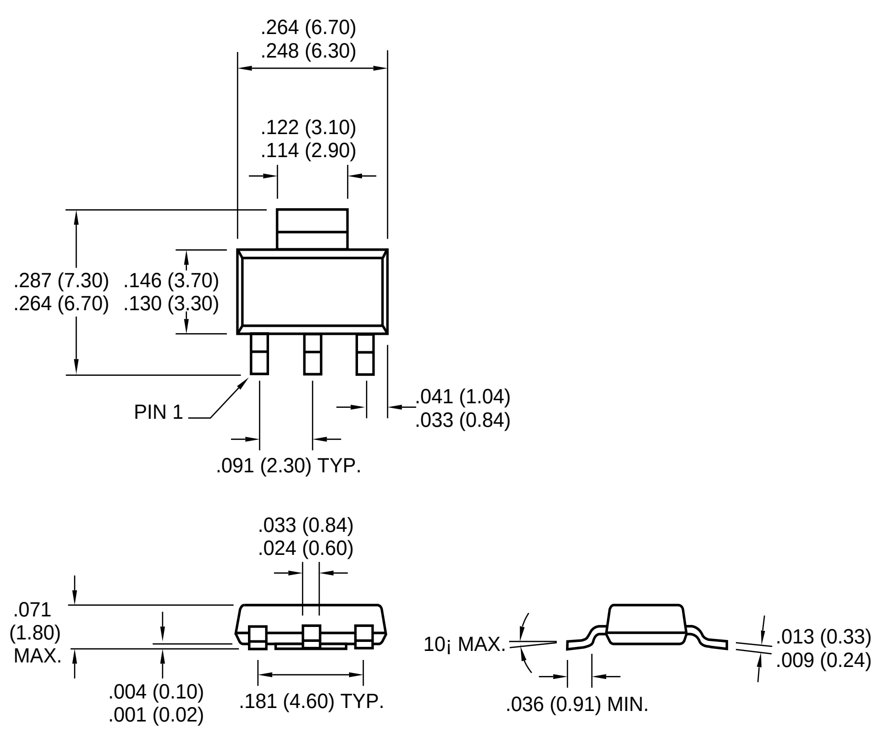
Reverse Reel Component Orientation
for RT Suffix Device
(Mark Upside Down)

Carrier Tape, Number of Components Per Reel and Reel Size

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
3-Pin SOT-223	12 mm	8 mm	4000	13 in

PACKAGE DIMENSIONS

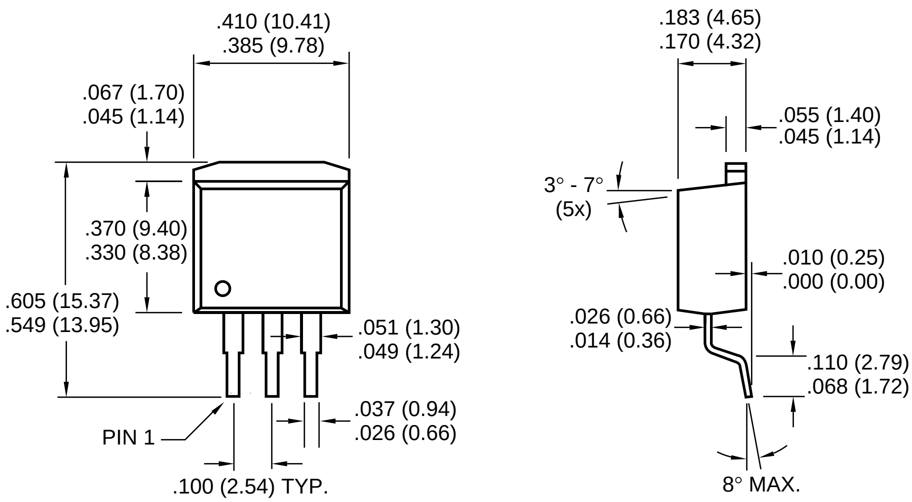
3-Pin SOT-223



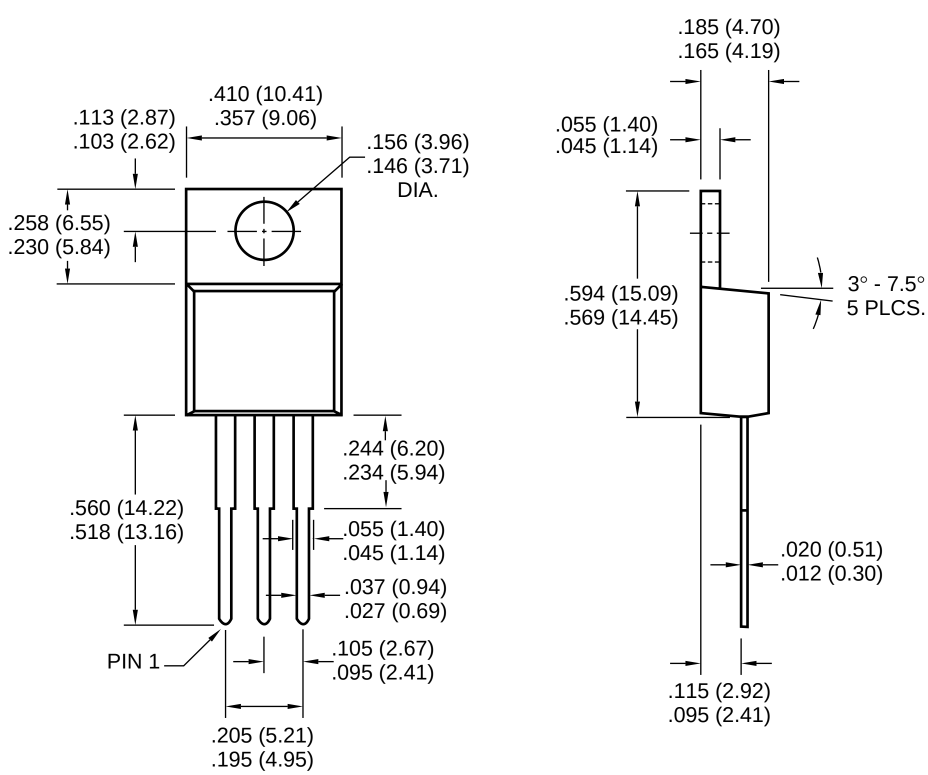
Dimensions: inches (mm)

PACKAGE DIMENSIONS

3-Pin DDPAK



3-Pin TO-220



Dimensions: inches (mm)

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